ST9625

Abstract

The subject matter of the invention is a method for removing a semiconductor wafer from a flat substrate. The subject matter of the invention is also a device for removing a semiconductor wafer from a polishing cloth of a double side polishing machine. The method is characterized in that a liquid is pressed through the substrate against the semiconductor wafer lying on the substrate, the semiconductor wafer being lifted from the substrate by the action of the liquid and then being picked up by a pick-up device.

This Sheet Has Been Replaced